Paul Truong

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Education

University of California, Davis — Davis, CA

Bachelor of Science in Electrical Engineering — *June 2025*

- **Relevant Coursework:** Circuit Analysis, Digital Systems, Computer Architecture, Programming Microcontrollers in C, Analog Circuits, Control Systems, Coding in MATLAB, Coding in Python
- **Activities:** Mech Keys @ UC Davis – Vice President, EE-Emerge, IEEE, Integrated Degree Program (IDP)
- **Awards:** ECE Texas Instruments Scholarship (2023)

Technical Skills

Languages: C, MATLAB, Python, RISC-V Assembly, Shell Scripting, Verilog
Software: Altera Quartus, Altium Designer, Cadence Allegro, Fusion360, LTspice, ModelSim, OrCAD
Hardware: Arduino, DC Power Supply, FPGAs, Multimeter, Oscilloscope, Rework, Soldering
Communication Protocols: I2C, I3C, SMBus, SPI, UART
Tools: Bash, Confluence, Git, Jira, Linux, PuTTY, Salesforce, Seismic, Tera Term, Unix, Windchill

Experience

Hardware Design Engineer — July 2025 – Present

Solidigm via Kelly OCG — *Rancho Cordova, CA*

- Applying DfX principles on enterprise SSDs, ensuring manufacturing compliance during strict design timelines
- Demonstrating proficiency in I2C, I3C, SMBus, and SPI protocols through both automated and manual validation
- Leading efforts for the Sacramento Hardware Team to become ISO-9001 compliant through facilitating Keysight device calibrations, lab cleanups, and internal equipment documentation

Hardware Engineering Co-op — Jan 2025 – July 2025

Solidigm — *Rancho Cordova, CA*

- Worked to perform signal integrity (SI) tests for I2C and SPI, adhering to their corresponding standards
- Reduced I2C manual SI testing time from 2 hours to roughly 20 minutes utilizing Keysight's automation platform
- Reviewed board layout against its schematic for proper routing and component placement

Field Applications Engineering Intern — June 2024 – Sep 2024

Western Digital — *San Jose, CA*

- Tracked qualification builds for the Amazon Devices account, leveraging Salesforce and Jira
- Spearheaded an initiative to build an in-office eMMC tester for field firmware updates (FFU) and failure analysis
- Created Linux environment and tester documentation for new users, improving system onboarding efficiency
- Delivered a critical FFU to 30 eMMCs, preventing multiple days of delay for Amazon Kuiper's next build launch

Camera Operator — Nov 2021 – Dec 2024

College of Engineering - UC Davis — *Davis, CA*

- Operated audiovisual systems for graduate courses, supporting Lawrence Livermore National Laboratory students
- Edited recorded lectures by splicing and amplifying audio for better comprehension, enhancing viewer experience

Projects

LED Puck Game – EE-Emerge | *Altium Designer, Arduino, Fusion360, Ultimaker Cura* — Jan 2023 – Jun 2023

- Tested 5+ different iterations of a puck enclosure in Fusion360 and Ultimaker Cura to make a cohesive design
- Soldered components onto a custom, circular ESP32 breakout board, integrating the LED strip and battery
- Enabled the device to be interacted through capacitive touch by shorting copper tape to the ESP32's GPIO pin